



Product Change Notification

Change Notification #: 114840 - 02
Change Title: Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS

Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS

PCN 114840-02, Product Design, Label, Product Material

Manufacturing Process Change for QSFP Cage Attach, Regulatory Label update for Korea/Taiwan, and Firmware Upgrade

Reason for Revision: Artwork Update

Date of Publication: October 27, 2016

Key Characteristics of the Change:

Product Design, Label, Product Material

Forecasted Key Milestones:

| | |
|---|--------------|
| Date Customer Must be Ready to Receive Post-Conversion Material: | Oct 07, 2016 |
|---|--------------|

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted

Description of Change to the Customer:

Reason for Revision: Artwork Update

| Affected Product Code | Product Description |
|-----------------------|--|
| 100HFA016LS | Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS |
| 100HFA016FS | Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS |

Overview of Changes:

Change 1: An issue has been identified with Intel® Omni-Path adapters that can result in unseating of the mechanical cage assembly over the Quad Small Form-factor Pluggable (QSFP) connector. Unseating of the QSFP cage assembly may prevent successful insertion of a cable QSFP module into a board connector due to guide misalignment. Electrical connectivity between the cable QSFP module and board QSFP connector is not compromised by a loose QSFP cage and QSFP modules successfully inserted and latched into board QSFP connectors will maintain expected electrical and thermal performance.

Change 2: Regulatory and Compliance Certifications were successfully acquired from Korea and Taiwan. The changes include the following:

- A. The regulatory label for the product will be updated with the Korean (KC/MSIP) and Taiwan (BSMI) marks.
- B. The Read Me First document will be updated to add the Regulatory Model Numbers, add a bar code near the part number, and remove an obsolete GNU license statement.
- C. [The packaging label will be updated](#) to reflect the KC labelling requirements

Change 3: The firmware shall be updated as follows, (reference release notes for 10.1 and 10.2):

- A. OptionROM UEFI firmware version 0x15 shall be replaced with version 0x29
- B. OptionROM hfi1_fabric_boot_7.efi shall be replaced with UNDI firmware 0x29
- C. OptionROM configuration file hfi1_platform.dat shall be replaced with hfi1_platform_10_1_0_0_129
- D. TMM firmware version 10.0.0.0.696 shall be replaced with version 10.2.00.154

Change 4: Removal of the boot over fabric portion of the OptionROM make the GPL language in the Read Me First document inaccurate, as it does not apply to any of the code loaded on the card.

Product Material Change Details:

Change 1: Intel have added a step to the manufacturing process for all Omni-Path adapters to solder QSFP cage assembly press-fit pins to the adapter laminate to eliminate the possibility of unseating of QSFP cage assemblies. This change does not impact form, fit or function of the adapter. The manufacturing process change implemented has been evaluated to ensure no quality, reliability or functional impacts to our customers.



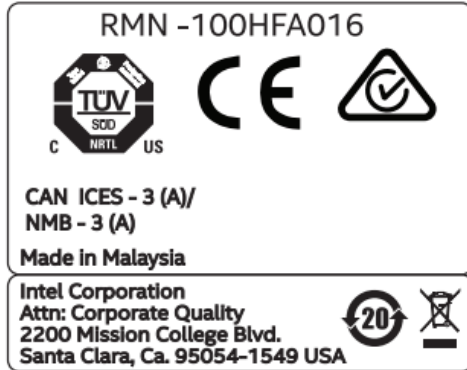
Unseated QSFP cage assembly



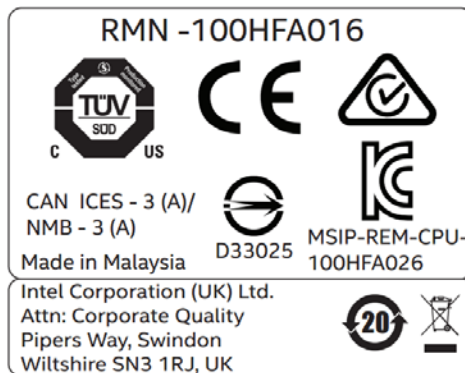
Properly Seated QSFP cage assembly

Change 2A: Regulatory Label showing the addition of the Korean and Taiwanese marks.

Before:



After:



Change 2B: The regulatory change will result in the addition of the Regulatory Model Numbers to the Read Me First Document. The RMF will also be revised to add a bar code under the Intel part number and to remove obsolete references to the GNU General Public License GNU.

Before:

Safety and Compliance
Regulatory Compliance Statements

Federal Communications Commission (FCC) Class A Statement

After:


Safety and Compliance
Regulatory Compliance Statements
Regulatory Model Numbers: 100HFA016, 100HFA018,
100HFA026

Federal Communications Commission (FCC) Class A Statement

Before:

| | |
|------------|---|
| J22171-001 | 1 |
|------------|---|

After:

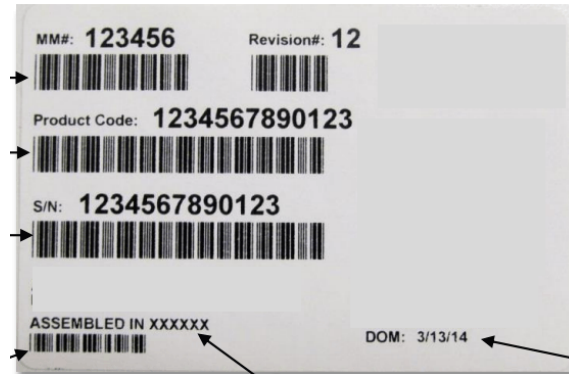
| | |
|---|---|
| J22171-002  | 1 |
|---|---|

Change 2C: Package labels will be changed to accommodate the Korean Regulatory requirements

The following data will be added to the individual box and non-serialized carton packaging labels for Korean requirements:

1. KC Mark
2. Korean Registration Number: MSIP-REM-CPU-100HFA026
3. Equipment Name: Intel Omni-Path Host Fabric Interface Adapter
4. Regulatory Model Number: 100HFA016
5. Applicant: Intel Corporation
6. Manufacturer: Flextronics Technology

Individual box label, before:



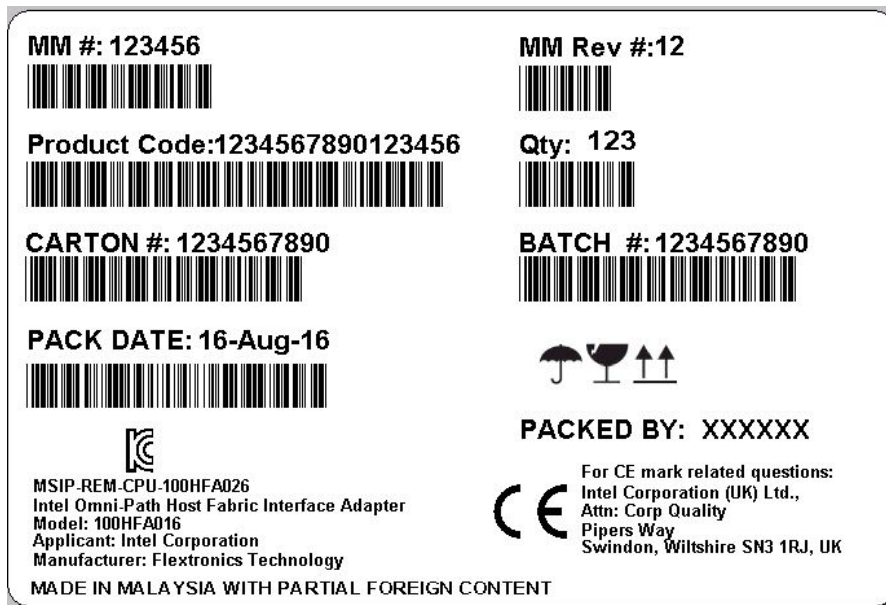
Individual box label, after:



Non-serialized carton label, before:



Non-serialized carton label, after:



Change 3: The firmware shall be updated as follows:

- A. OptionROM UEFI firmware version 0x15 shall be replaced with version 0x29
- B. OptionROM hfi1_fabric_boot_7.efi shall be replaced with UNDI firmware 0x29
- C. OptionROM configuration file hfi1_platform.dat shall be replaced with hfi1_platform_10_1_0_0_129
- D. TMM firmware version 10.0.0.0.696 shall be replaced with version 10.2.00.154

Change 4: Removal of GNU General Public License reference in the Read Me First document.

Before:

rights therein. Contractor or Manufacturer is Intel Corporation, 2200 Mission College Blvd., Santa Clara, CA 95052.

GNU General Public License GNU

This product contains firmware for Boot over Fabric functionality that is covered under the GNU General Public License, version 2, as published by the Free Software Foundation.

Legal

No license (express or implied, by estoppel or otherwise) to any intellectual property rights is granted by this document.

After:

rights therein. Contractor or Manufacturer is Intel Corporation, 2200 Mission College Blvd., Santa Clara, CA 95052.

Legal

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Customer Impact of Change and Recommended Action:

Any adapters identified through visual inspection to have a loose or unseated QSFP cage assembly should be RMA'd to Intel for replacement or credit according to their warranty coverage. Customers with unopened adapters shipped from Intel before May 16, 2016 may also return their adapters to Intel for replacement or credit according to their warranty coverage. Adapters functioning properly in running systems require no action.

Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

| Product Code | MM# | Pre Change MM# Rev | Post Change MM# Rev | Pre Change TA | Post Change TA | Pre Change AS | Post Change AS | Pre Change PBA | Post Change PBA |
|--------------|--------|-----------------------|------------------------|---------------|----------------|---------------|----------------|----------------|-----------------|
| 100HFA016FS | 945671 | 02 | 03 | J29320-002 | J29320-003 | J29321-002 | J29321-003 | J10547-019 | J10547-020 |
| 100HFA016LS | 948159 | 12 | 13 | J10549-021 | J10549-022 | J10548-021 | J10548-022 | J10547-019 | J10547-020 |

PCN Revision History:

| Date of Revision: | Revision Number: | Reason: |
|----------------------------------|--------------------|---|
| September 1, 2016 | 00 | Originally Published PCN |
| October 3, 2016 | 01 | Reason for Revision: Include additional information in the Products Affected table, revise Ready to Receive Date, Firmware Upgrade, and Modify Read Me First Document |
| October 27, 2016 | 02 | Artwork Update |



Product Change Notification

114840 - 02

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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